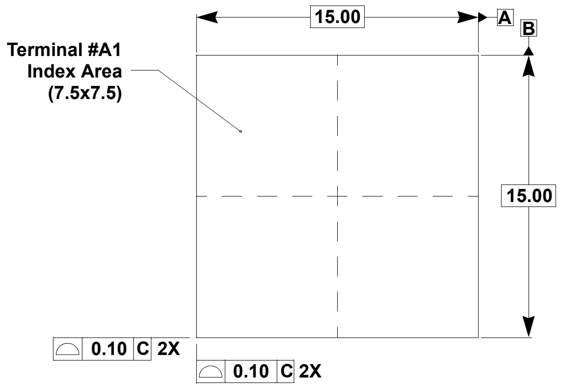
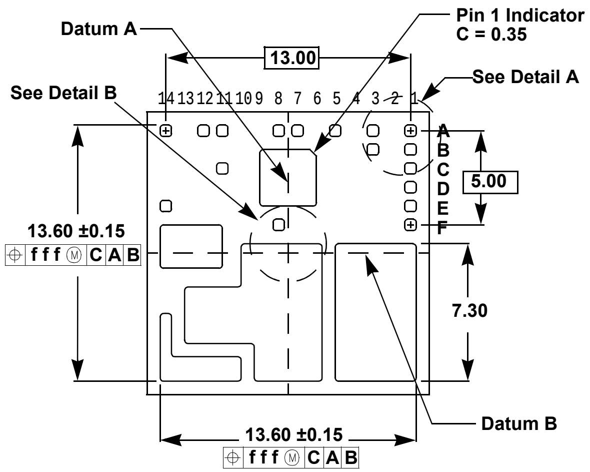
Package Outline Drawing

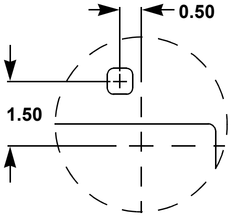
Y22.15x15
22 I/O 15mmx15mmx3.6mm Custom HDA Module
Rev 3, 9/18



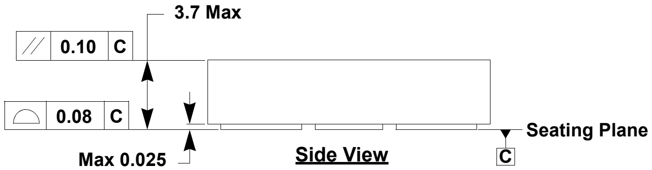
Top View



Bottom View



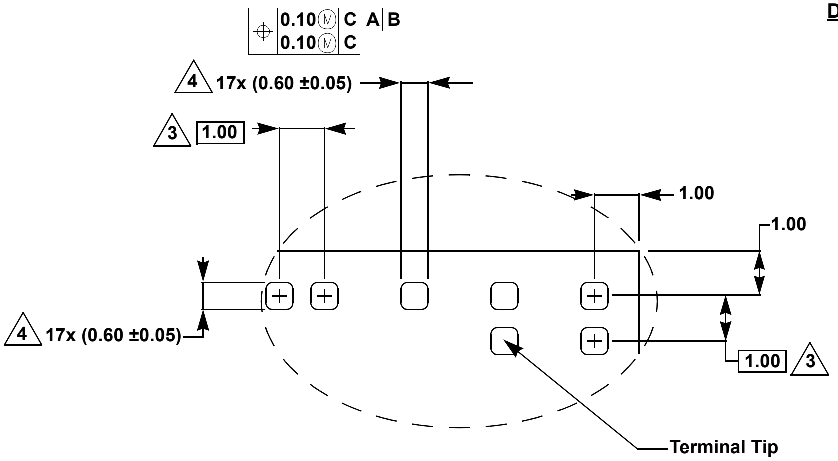
Detail B



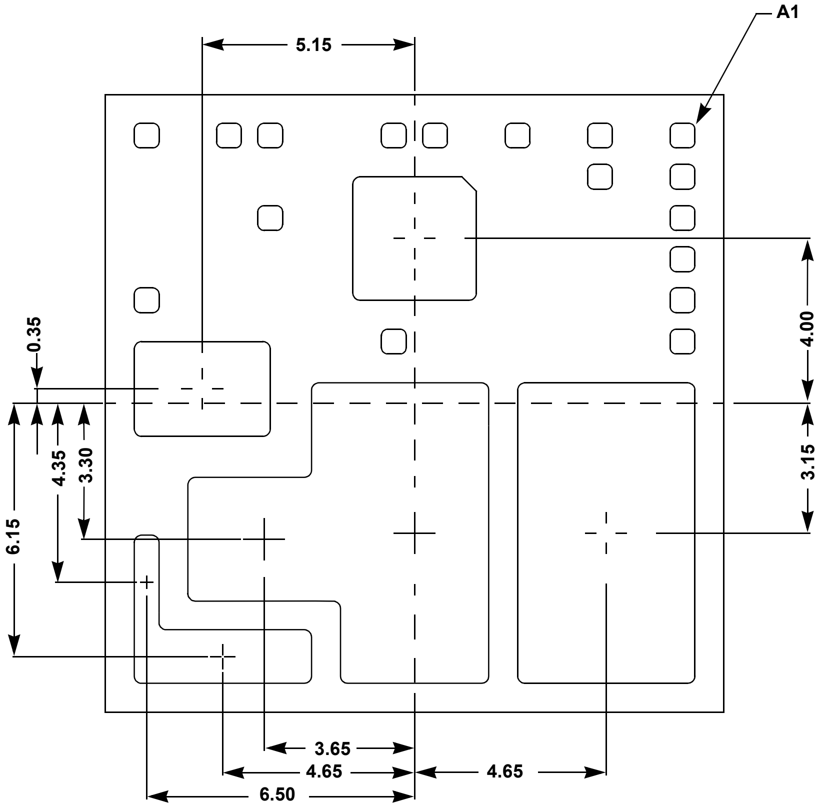
Side View

Notes:

1. All dimensions are in millimeters.
2. All tolerances ± 0.10mm, unless otherwise noted.
3. Represents the basic land grid pitch.
4. The total number of smaller I/O pads is 17. All 17 I/O's are centered in a fixed row and column matrix at 1.0mm pitch BSC.
5. Dimensioning and tolerancing per ASME Y14.5M-1994.
6. Tolerance for exposed DAP edge location dimension.

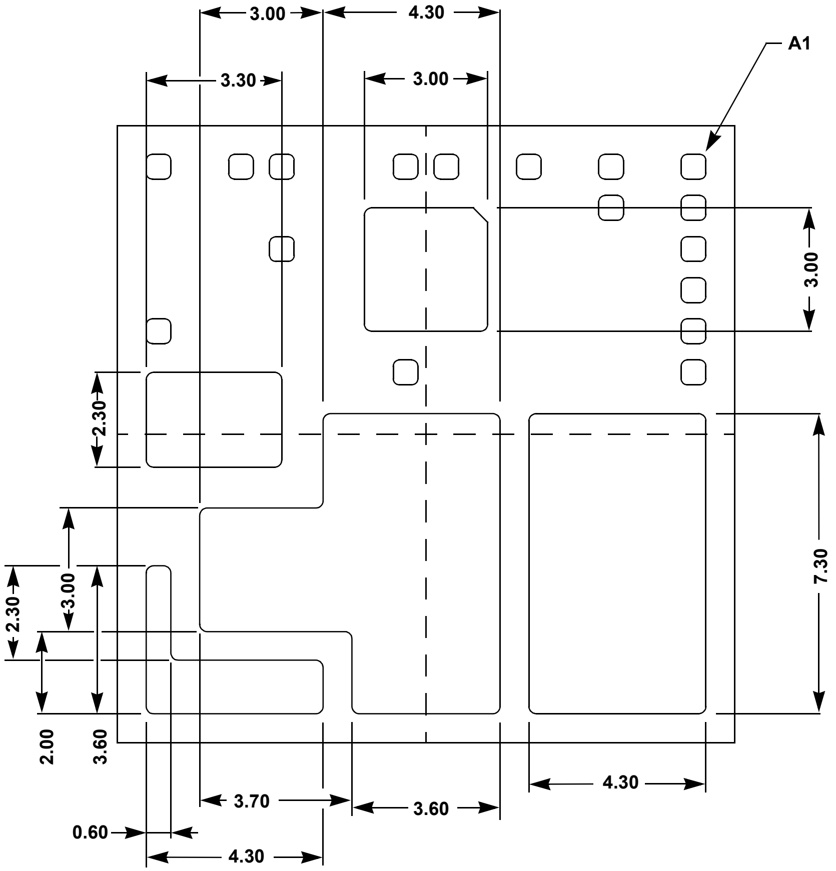


Detail A



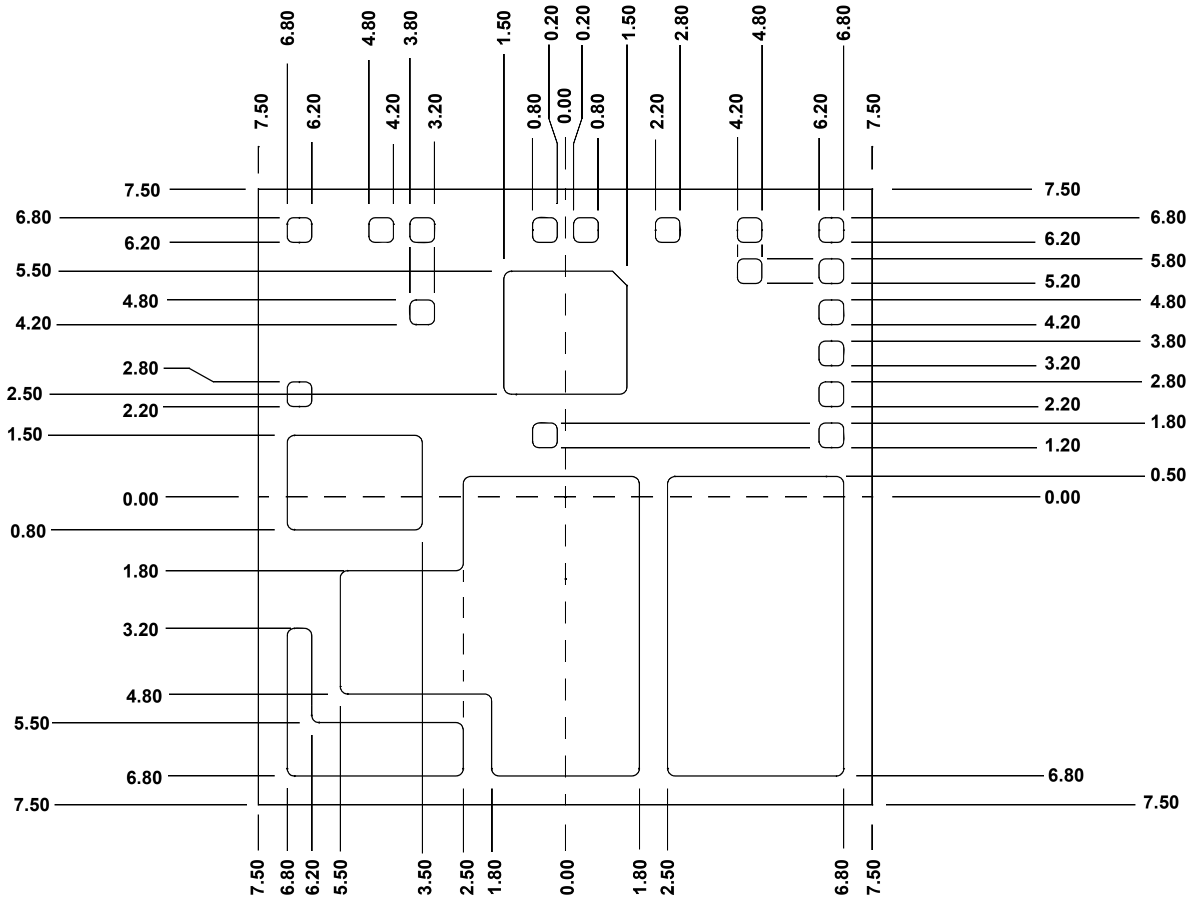
Centerline Position Details for the 5 Exposed DAPs

Bottom View



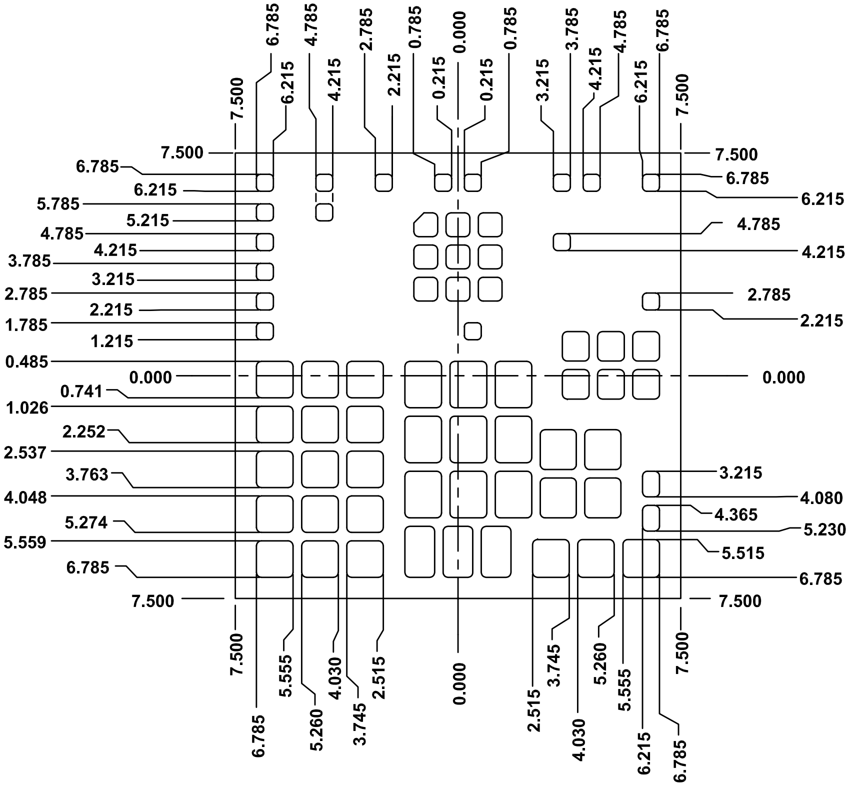
Dimensional Details for the 5 Exposed PADs

Bottom View



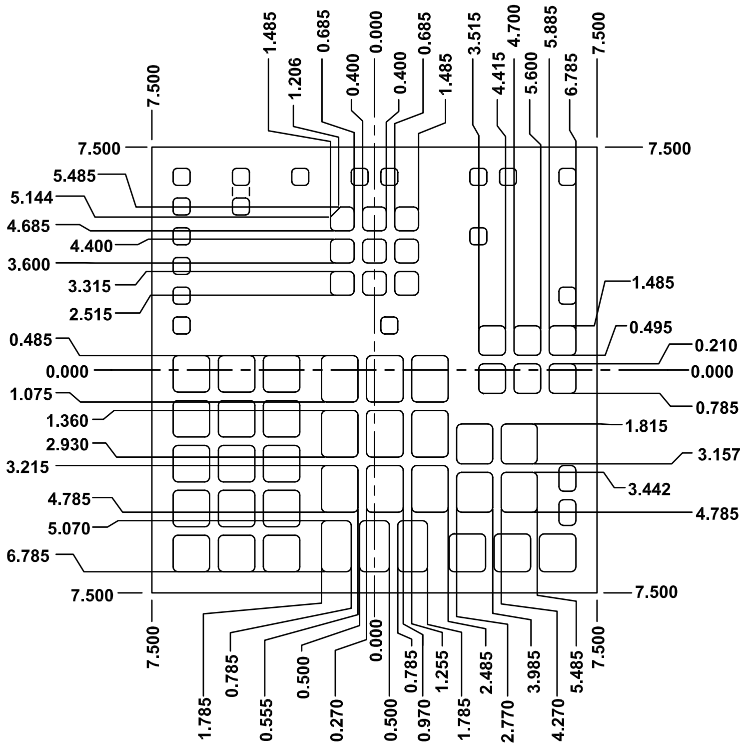
Terminal and Pad Edge Details

Bottom View



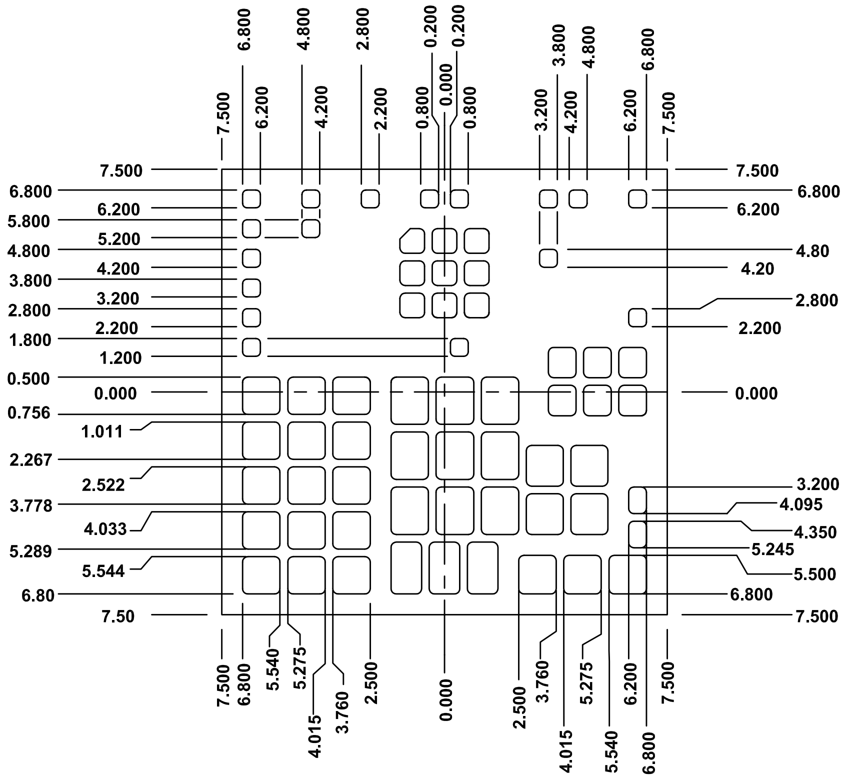
Suggested Stencil Pattern - 1

Top View



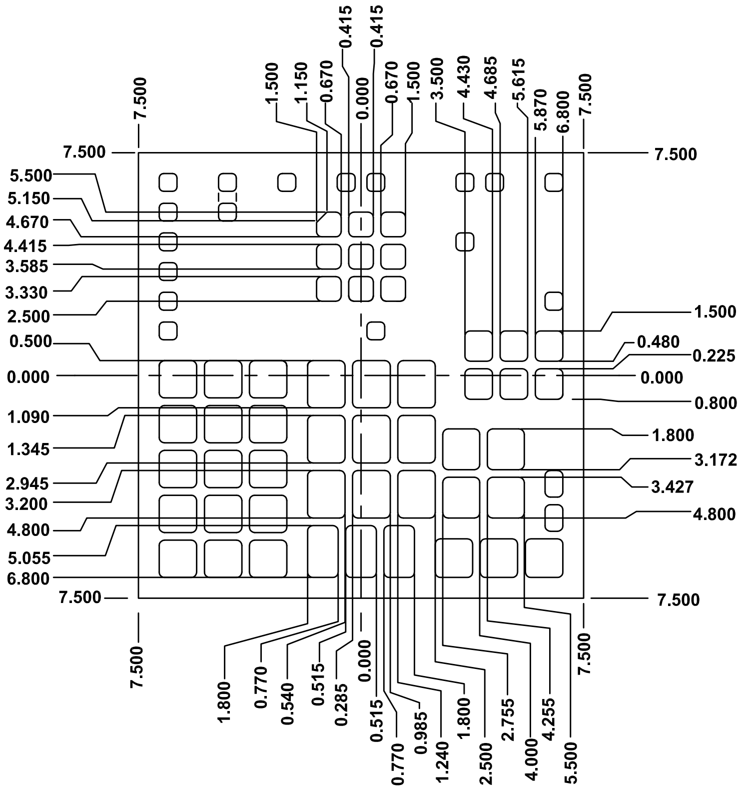
Suggested Stencil Pattern - 2

Top View



Suggested PCB Land Pattern - 1

Top View



Suggested PCB Land Pattern - 2

Top View